



PMEG2005ELD

20 V, 0.5 A low V_F MEGA Schottky barrier rectifier

Rev. 1 — 4 May 2011

Product data sheet

1. Product profile

1.1 General description

Planar Maximum Efficiency General Application (MEGA) Schottky barrier rectifier with an integrated guard ring for stress protection, encapsulated in a SOD882D leadless ultra small Surface-Mounted Device (SMD) plastic package with visible and solderable side pads.

1.2 Features and benefits

- Forward current: $I_F \leq 0.5$ A
- Reverse voltage: $V_R \leq 20$ V
- Low forward voltage: $V_F \leq 500$ mV
- Low reverse current
- AEC-Q101 qualified
- Solderable side pads
- Package height typ. 0.37 mm
- Ultra small and leadless SMD plastic package

1.3 Applications

- Low voltage rectification
- High efficiency DC-to-DC conversion
- Switch Mode Power Supply (SMPS)
- Reverse polarity protection
- Low power consumption applications
- Ultra high-speed switching

1.4 Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$I_{F(AV)}$	average forward current	square wave; $\delta = 0.5$; $f = 20$ kHz				
		$T_{amb} \leq 85$ °C	[1]	-	0.5	A
		$T_{sp} \leq 130$ °C	-	-	0.5	A
I_R	reverse current	$V_R = 10$ V	-	5	30	μ A
V_R	reverse voltage		-	-	20	V
V_F	forward voltage	$I_F = 500$ mA	[2]	450	500	mV

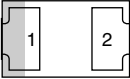
[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated, mounting pad for cathode 1 cm².

[2] Pulse test: $t_p \leq 300$ μ s; $\delta \leq 0.02$.

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2. Pinning information

Table 2. Pinning

Pin	Description	Simplified outline	Graphic symbol
1	cathode		
2	anode		

Transparent top view

[1] The marking bar indicates the cathode.

3. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PMEG2005ELD	-	leadless ultra small plastic package; 2 terminals; body 1 × 0.6 × 0.4 mm	SOD882D

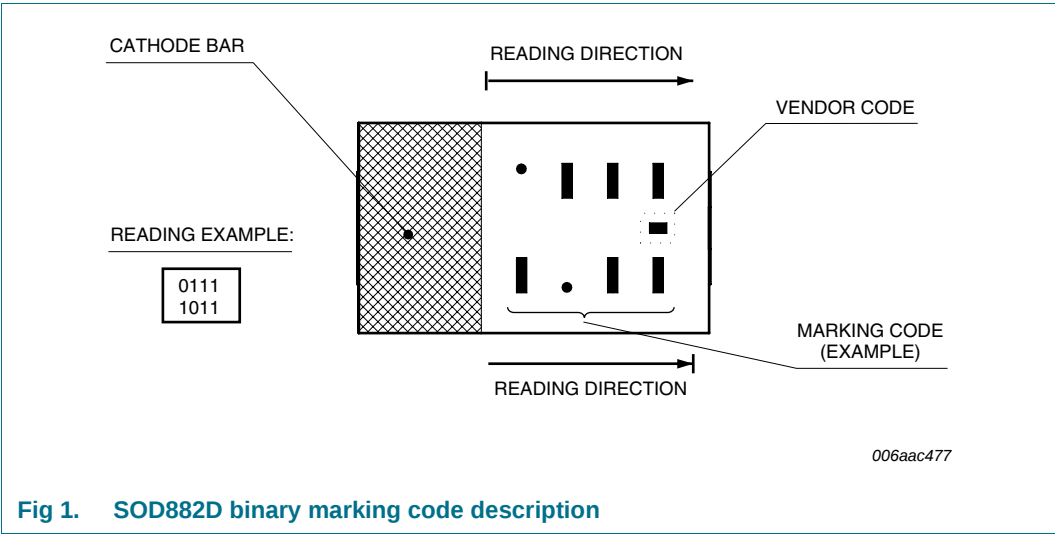
4. Marking

Table 4. Marking codes

Type number	Marking code ^[1]
PMEG2005ELD	0101 0000

[1] For SOD882D binary marking code description, see [Figure 1](#).

4.1 Binary marking code description



5. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_R	reverse voltage		-	20	V
$I_{F(AV)}$	average forward current	square wave; $\delta = 0.5$; $f = 20$ kHz			
		$T_{amb} \leq 85$ °C	[1] -	0.5	A
		$T_{sp} \leq 130$ °C	-	0.5	A
I_{FRM}	repetitive peak forward current	$t_p \leq 1$ ms; $\delta \leq 0.25$	-	2.5	A
I_{FSM}	non-repetitive peak forward current	square wave; $t_p = 8$ ms	[2] -	3	A
P_{tot}	total power dissipation	$T_{amb} \leq 25$ °C	[3] -	340	mW
			[1] -	660	mW
			[4] -	1000	mW
T_j	junction temperature		-	150	°C
T_{amb}	ambient temperature		-55	+150	°C
T_{stg}	storage temperature		-65	+150	°C

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm².

[2] $T_j = 25$ °C prior to surge.

[3] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[4] Device mounted on a ceramic PCB, Al₂O₃, standard footprint.

6. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1][2]	-	-	370 K/W
			[1][3]	-	-	190 K/W
			[1][4]	-	-	125 K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point		[5]	-	-	50 K/W

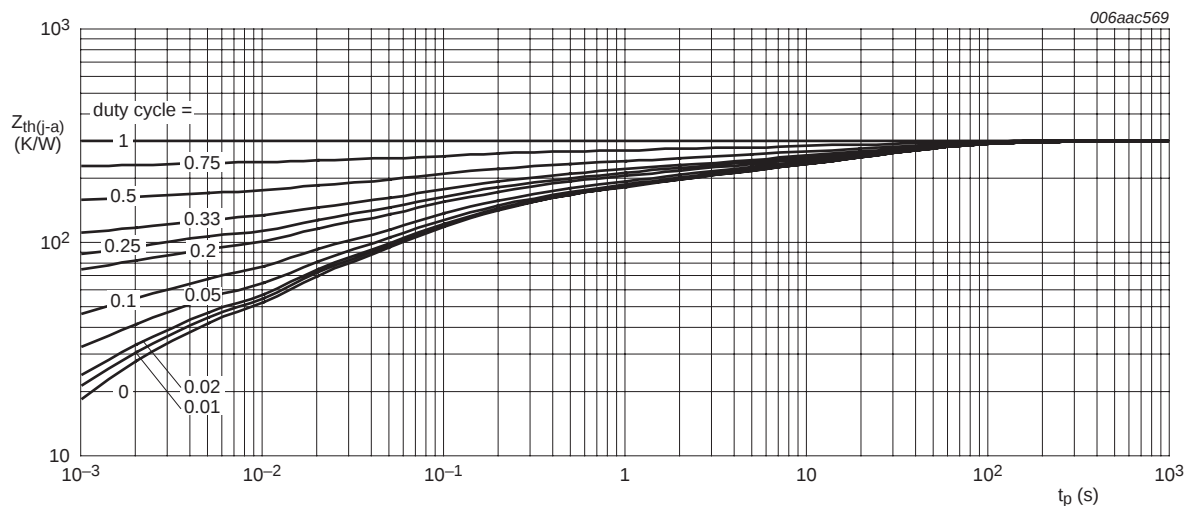
[1] For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses P_R are a significant part of the total power losses.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm².

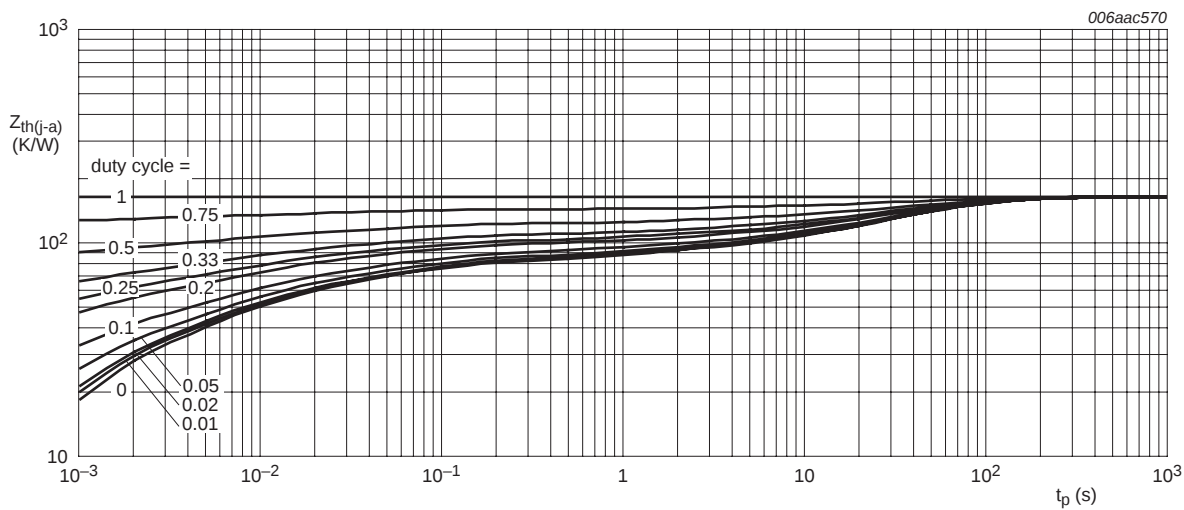
[4] Device mounted on a ceramic PCB, Al₂O₃, standard footprint.

[5] Soldering point of cathode tab.



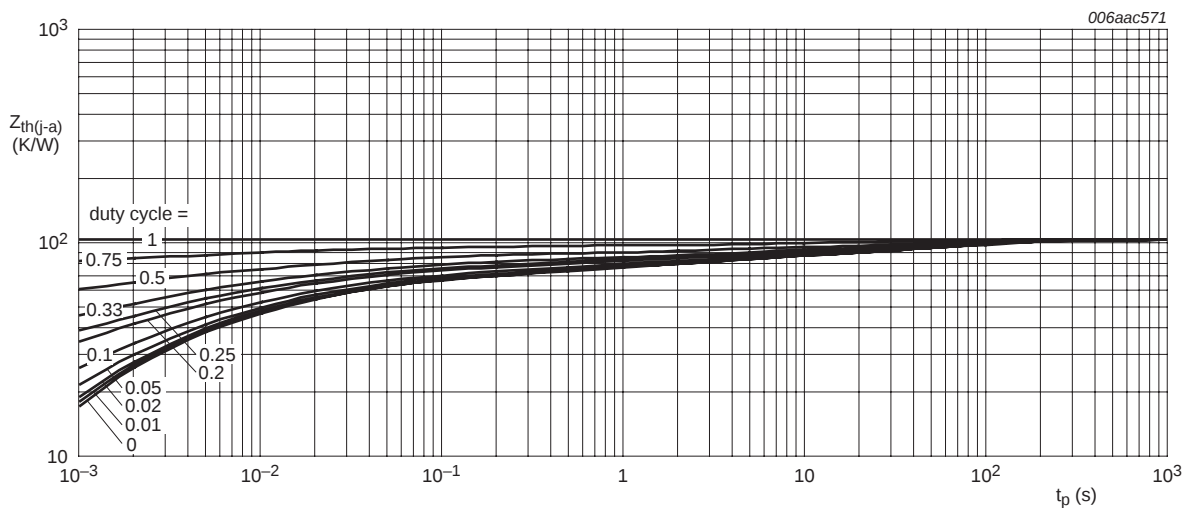
FR4 PCB, standard footprint

Fig 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



FR4 PCB, mounting pad for cathode 1 cm²

Fig 3. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



Ceramic PCB, Al₂O₃, standard footprint

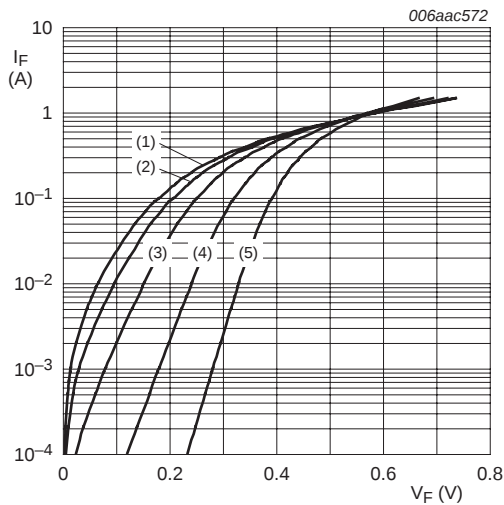
Fig 4. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

7. Characteristics

Table 7. Characteristics
T_{amb} = 25 °C unless otherwise specified.

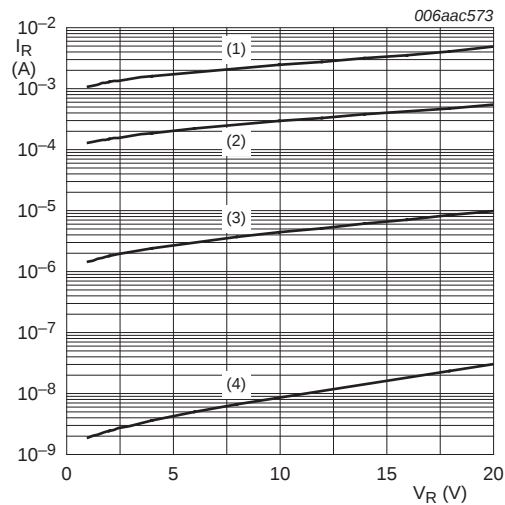
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V _F	forward voltage		[1]			
		I _F = 0.1 mA	-	115	180	mV
		I _F = 1 mA	-	175	240	mV
		I _F = 10 mA	-	240	290	mV
		I _F = 100 mA	-	320	380	mV
		I _F = 500 mA	-	450	500	mV
I _R	reverse current	V _R = 10 V	-	5	30	μA
C _d	diode capacitance	V _R = 1 V; f = 1 MHz	-	24	30	pF
t _{rr}	reverse recovery time		[2]	7	-	ns

[1] Pulse test: t_p ≤ 300 μs; δ ≤ 0.02.
[2] When switched from I_F = 10 mA to I_R = 10 mA; R_L = 100 Ω; measured at I_R = 1 mA.



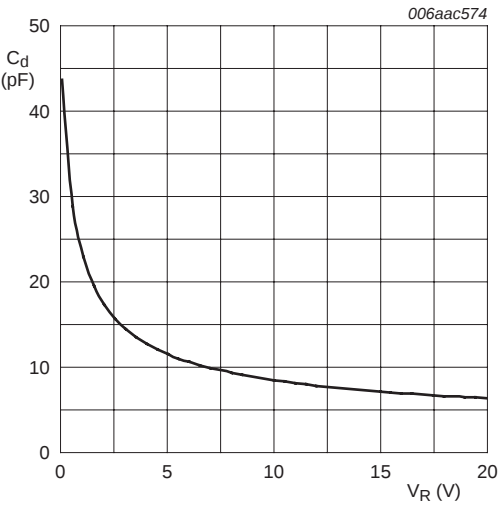
- (1) $T_j = 150\text{ °C}$
- (2) $T_j = 125\text{ °C}$
- (3) $T_j = 85\text{ °C}$
- (4) $T_j = 25\text{ °C}$
- (5) $T_j = -40\text{ °C}$

Fig 5. Forward current as a function of forward voltage; typical values



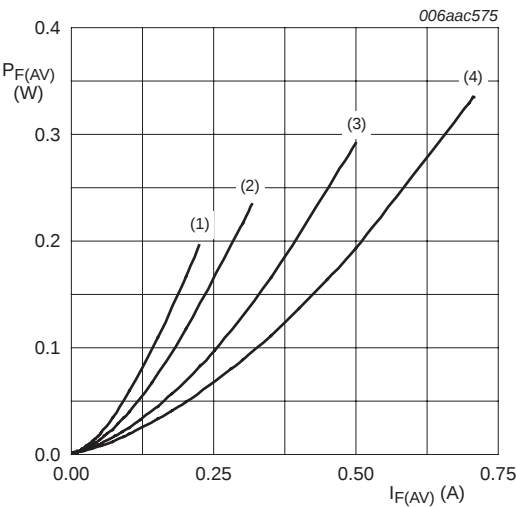
- (1) $T_j = 125\text{ °C}$
- (2) $T_j = 85\text{ °C}$
- (3) $T_j = 25\text{ °C}$
- (4) $T_j = -40\text{ °C}$

Fig 6. Reverse current as a function of reverse voltage; typical values



$f = 1\text{ MHz}$; $T_{\text{amb}} = 25\text{ }^{\circ}\text{C}$

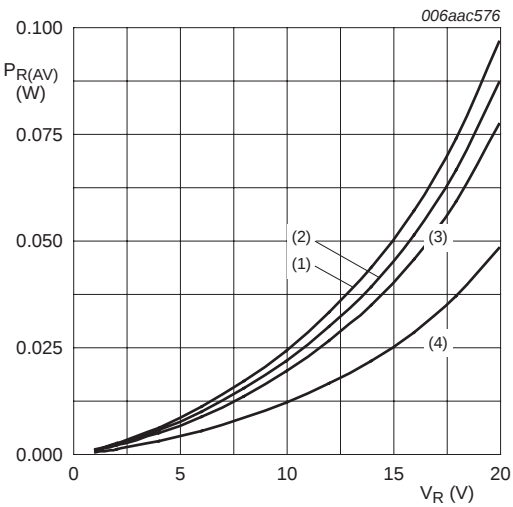
Fig 7. Diode capacitance as a function of reverse voltage; typical values



$T_j = 150\text{ }^{\circ}\text{C}$

- (1) $\delta = 0.1$
- (2) $\delta = 0.2$
- (3) $\delta = 0.5$
- (4) $\delta = 1$

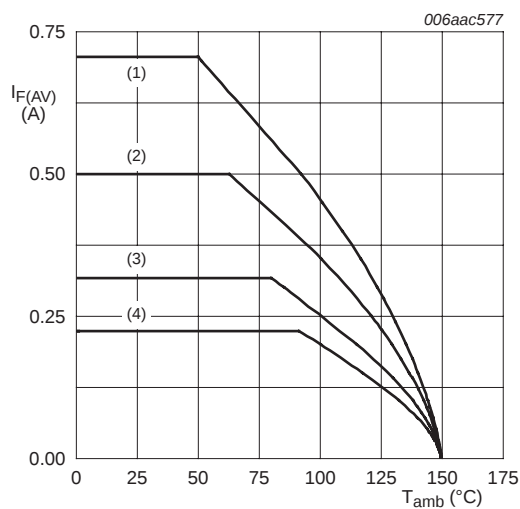
Fig 8. Average forward power dissipation as a function of average forward current; typical values



$T_j = 125\text{ }^{\circ}\text{C}$

- (1) $\delta = 1$
- (2) $\delta = 0.9$
- (3) $\delta = 0.8$
- (4) $\delta = 0.5$

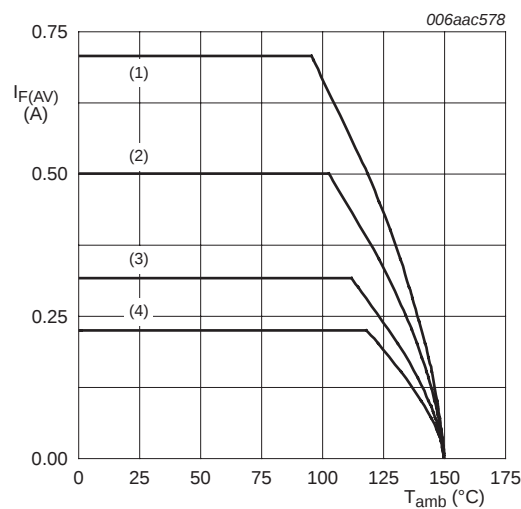
Fig 9. Average reverse power dissipation as a function of reverse voltage; typical values



FR4 PCB, standard footprint
 $T_j = 150$ °C

- (1) $\delta = 1$; DC
- (2) $\delta = 0.5$; $f = 20$ kHz
- (3) $\delta = 0.2$; $f = 20$ kHz
- (4) $\delta = 0.1$; $f = 20$ kHz

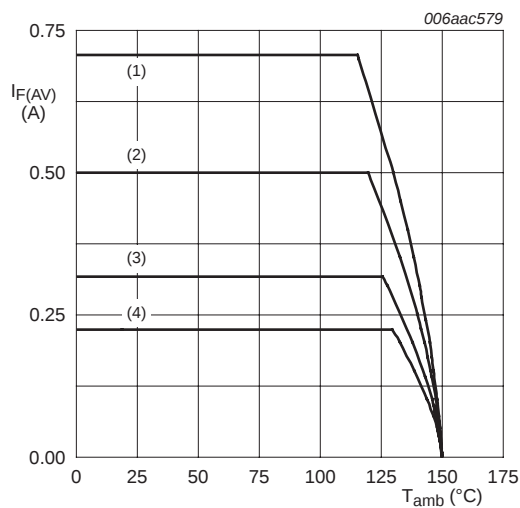
Fig 10. Average forward current as a function of ambient temperature; typical values



FR4 PCB, mounting pad for cathode 1 cm²
 $T_j = 150$ °C

- (1) $\delta = 1$; DC
- (2) $\delta = 0.5$; $f = 20$ kHz
- (3) $\delta = 0.2$; $f = 20$ kHz
- (4) $\delta = 0.1$; $f = 20$ kHz

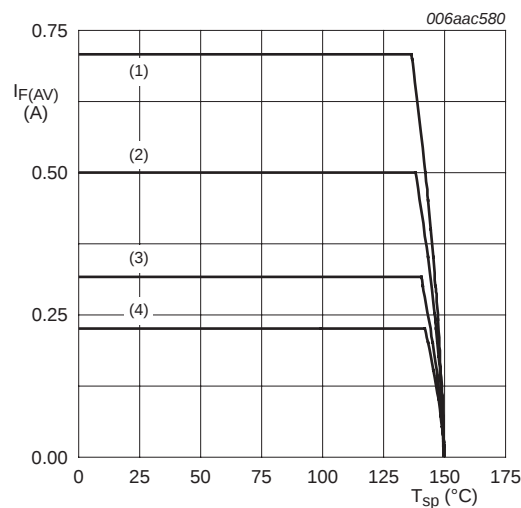
Fig 11. Average forward current as a function of ambient temperature; typical values



Ceramic PCB, Al₂O₃, standard footprint
 $T_j = 150$ °C

- (1) $\delta = 1$; DC
- (2) $\delta = 0.5$; $f = 20$ kHz
- (3) $\delta = 0.2$; $f = 20$ kHz
- (4) $\delta = 0.1$; $f = 20$ kHz

Fig 12. Average forward current as a function of ambient temperature; typical values



$T_j = 150$ °C
(1) $\delta = 1$; DC
(2) $\delta = 0.5$; $f = 20$ kHz
(3) $\delta = 0.2$; $f = 20$ kHz
(4) $\delta = 0.1$; $f = 20$ kHz

Fig 13. Average forward current as a function of solder point temperature; typical values

8. Test information

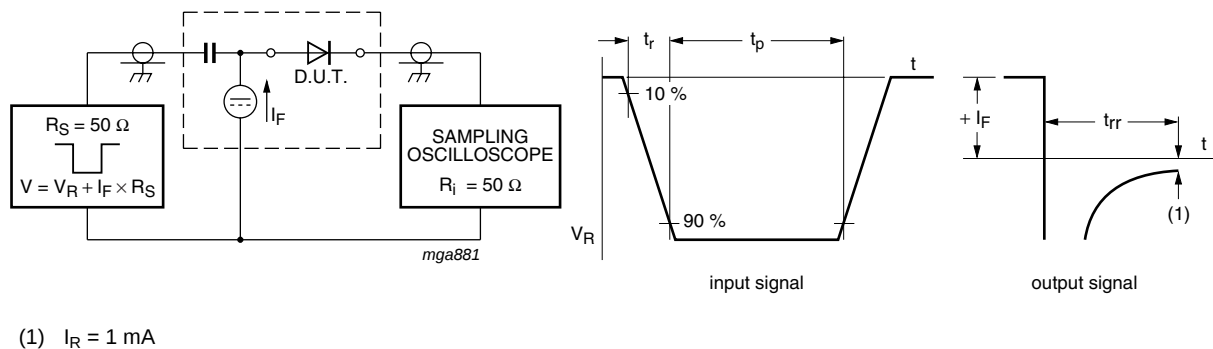


Fig 14. Reverse recovery time test circuit and waveforms

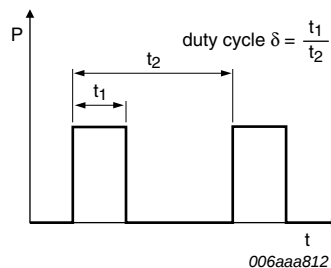


Fig 15. Duty cycle definition

The current ratings for the typical waveforms as shown in [Figure 10](#), [11](#), [12](#) and [13](#) are calculated according to the equations: $I_{F(AV)} = I_M \times \delta$ with I_M defined as peak current, $I_{RMS} = I_{F(AV)}$ at DC, and $I_{RMS} = I_M \times \sqrt{\delta}$ with I_{RMS} defined as RMS current.

8.1 Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard *Q101 - Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.

12. Revision history

Table 9. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
PMEG2005ELD v.1	20110504	Product data sheet	-	-

13. Legal information

13.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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